



Materials for Power Devices and Electronic Components

Epoxy Underfills



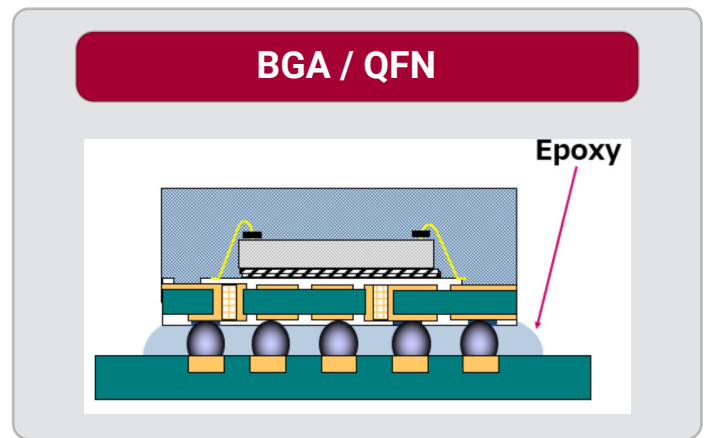
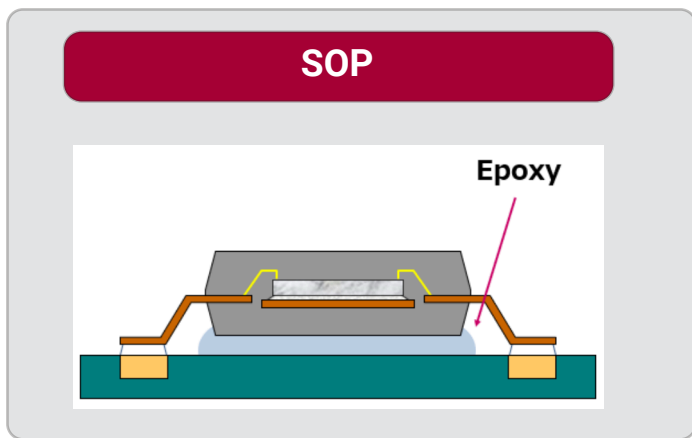
Mounted Device Protection & Better Insulation

Underfill, DAM

Charateristics

- Easy handling for manufacturing
- No need to remove flux
- Good pot life

Application in Automotive



	Condition	Unit	T-700/R-5902	R3501-01	R5011-X08
Application			Secondary UF	Secondary UF	DAM Corner Bond
Characteristic			Flux compatibility	Good pot life	High reliability Low temperature cure
Curing Condition			150 °C / 1 h	160 °C / 40 min	120 °C / 1 h
Appearance			Black liquid	Black liquid	Black liquid
Viscosity	25 °C	Pa*s	8	25	290
Thixotropic Index	25 °C	-	-	-	3.5
CTE 1	$\leq T_g$	$\times 10^{-6}/K$	17	26	20
Tg (DMA)		°C	186	160	125 (TMA)
Modulus	25 °C	GPa	11	9	-

